

# N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)	
30	$0.005 \text{ at V }_{GS} = 10 \text{ V}$	70 <sup>d</sup>	67	
30	$0.0063$ at $V_{GS} = 4.5 \text{ V}$	70 <sup>d</sup>	07	

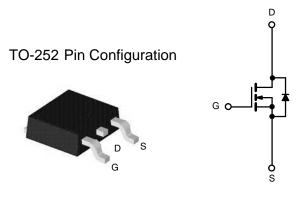
#### **FEATURES**

- DT-Trench Power MOSFET
- 100 % R<sub>q</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



#### **APPLICATIONS**

- Power Supply
  - Secondary Synchronous Rectification
- DC/DC Converter



Top View		

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_C = 25$ °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V		
Gate-Source Voltage	V <sub>GS</sub>	± 20	1 v		
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I-	70 <sup>d</sup>		
Continuous Diain Current (1) = 130 C)	T <sub>C</sub> = 70 °C	I <sub>D</sub>	60 <sup>d</sup>	A	
Pulsed Drain Current	I <sub>DM</sub>	210			
Avalanche Current		I <sub>AS</sub>	45		
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	101	mJ	
Mariana Barra Birainatia a	T <sub>C</sub> = 25 °C	В	78.1 <sup>b</sup>	10/	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	P <sub>D</sub>	3.1	W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

N-Channel MOSFET

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)	R <sub>thJC</sub>	1.6		

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.c. When Mounted on 1" square PCB (FR-4 material).
- d. Package limited.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$ $V_{DS} = 0 \text{ V, } I_{D} = 250  \mu\text{A}$ 30				V		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		2.5	- V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nΑ	
		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μA	
		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 22 A		0.0030	0.005		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0046	0.0063	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		110		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			3535			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$		680		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			400			
Total Gate Charge <sup>c</sup>	Qg			67	100		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		10.5		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			12.2			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.3	1.4	2.8	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			11	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 1.5 $\Omega$		10	20		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		35	53	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			10	20	1	
Drain-Source Body Diode Ratings ar	nd Characteris	stics T <sub>C</sub> = 25 °C <sup>b</sup>					
Continuous Current	Is				70	^	
Pulsed Current	I <sub>SM</sub>				210	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		0.83	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			41	62	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	$I_F = 10 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		2	3	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			40	60	nC	

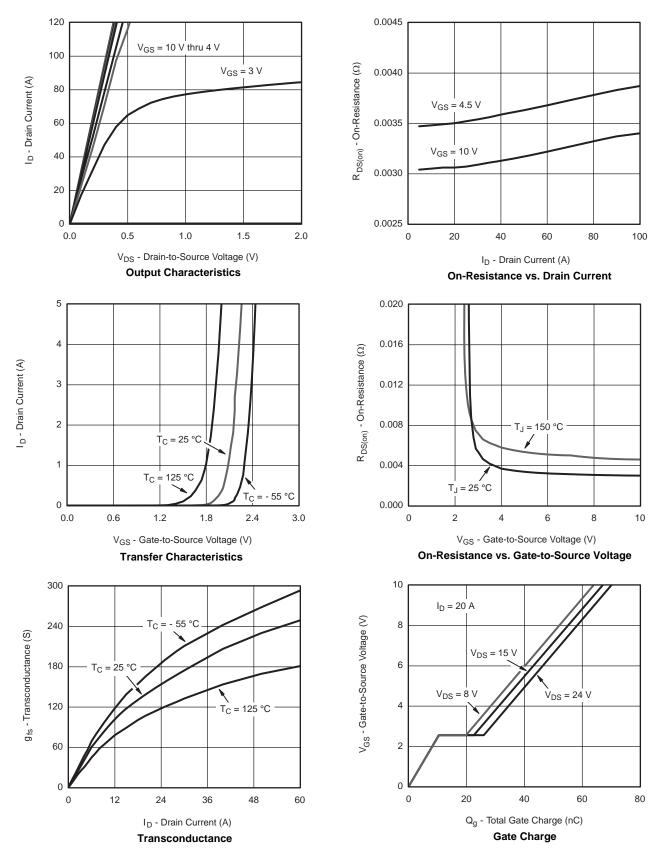
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$  b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

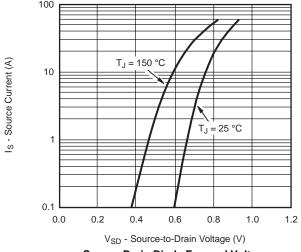


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

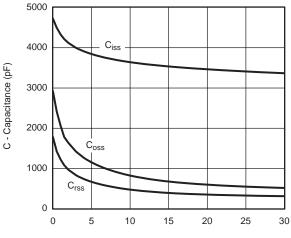




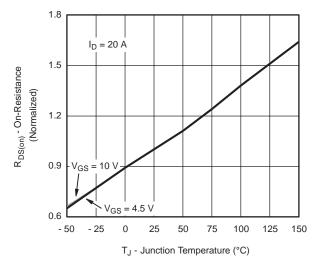
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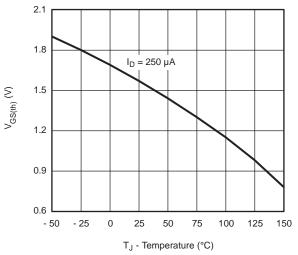




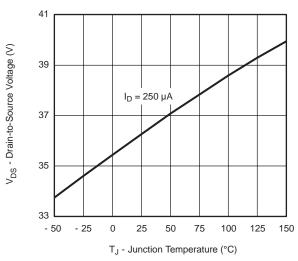
 $V_{DS}$  - Drain-to-Source Voltage (V) Capacitance



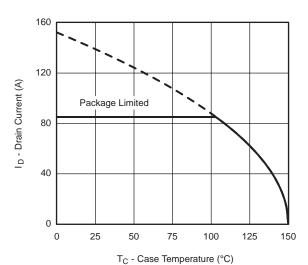
On-Resistance vs. Junction Temperature



Threshold Voltage



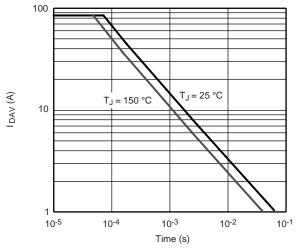
Drain Source Breakdown vs. Junction Temperature



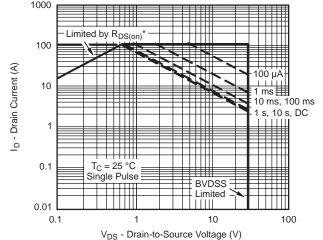
**Current Derating** 



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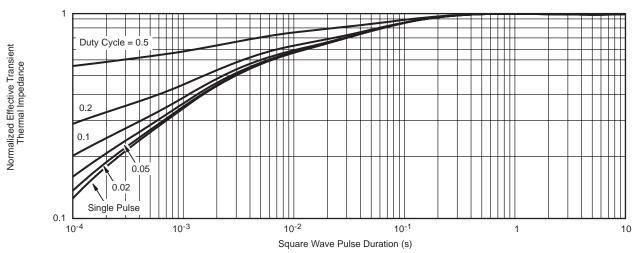


Single Pulse Avalanche Current Capability vs. Time



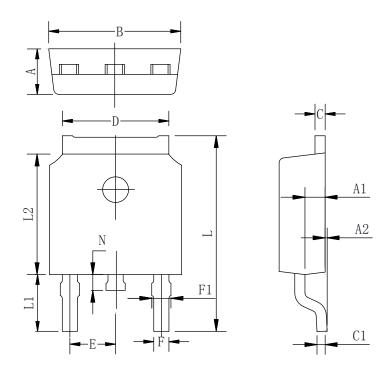
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

#### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

# **TO-252-2L PACKAGE OUTLINE**



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max	
A	2.10	2.30	2.50	
A1	0.88	1.01	1.16	
A2	0.00	0.15	0.28	
В	6.40	6.60	6.80	
С	0.42	0.50	0.63	
C1	0.42	0.50	0.63	
D	5.08	5.32	5.65	
Е	2.286 TYP			
F	0.63	0.76	0.89	
F1	0.64	0.86	1.08	
L	9.30	9.90	10.80	
L1	2.4	2.8	3.6	
L2	5.90	6.10	6.55	
N	0.57	0.80	1.05	

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